

Appl. No. : known
Filed : crewith

a1 on the holder and are constructed to individually release or grip a chip-carrier plate in a similar angular position of the holder.

IN THE SPECIFICATION:

Page 1, immediately after the title, please insert:

Related Applications

a2 This application claims the benefit of the European application 01 126 708.5 filed November 8, 2001.

Please amend the paragraph beginning on page 1, line 11, as follows:

Background of the Invention

Field of the Invention

a3 The invention relates to a mechanism for exchanging chip-carrier plates in a hybrid chip-bonding machine, in particular to an automatic hybrid chip-bonding machine.

Description of the Related Art

Please amend the paragraph beginning on page 3, line 16, as follows:

Summary of the Invention

a4 It is the objective of the present invention to disclose an improved mechanism for exchanging chip-carrier plates as well as a method of operating such a mechanism, with which still greater operating efficiency can be attained, and hence lower production costs for chip bonding.

Please amend the paragraph beginning on page 5, line 26, as follows:

Brief Description of the Drawings

a5 A preferred embodiment of a chip-carrier-plate system in accordance with the invention is described in greater detail in the following, with reference to the attached drawings, wherein

Fig. 1 shows a schematic overall view of the components of an automatic hybrid chip-bonding machine;

Please amend the paragraph beginning on page 6, line 3, as follows:

Detailed Description of the Preferred Embodiment

Fig. 1 shows the principles of construction of an automatic hybrid chip-bonding machine 1, which comprises on one hand an epoxy die bonder 2 and on the other hand a die collet system 4 for chip assembly, which are the actual processing stations. The chip-bonding machine 1 further comprises a chip-delivery system 6 and a chip-detaching system 8. The chip-delivery system 6 includes a magazine 10 to contain a plurality of chip-carrier plates as well as the actual delivery mechanism, which is the object of the invention. Chip-bonding machines of this kind have long been known, so that their construction and the interaction of the main components need not be described further here.

IN THE CLAIMS:

Please amend the Claims as follows:

WHAT IS CLAIMED IS:

1. (Amended) A mechanism for exchanging chip-carrier plates for use in a hybrid chip-bonding machine having a chip-detaching system and a common base element, the mechanism comprising:

a plurality of chip-carrier plates;

a magazine to store the plurality of chip-carrier plates;

a transport arrangement having a first and a second clamping device that are disposed on a movable holder in a manner such that the transport arrangement is designed to remove a selected chip-carrier plate from the magazine, deliver the selected chip-carrier plate to a processing station of the chip-detaching system, and after processing remove the selected chip-carrier plate from the processing station and deposit the selected chip-carrier plate in the magazine;